The effect of current on insulating ceramic materials during SPS

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Ryu Jonghun



1. Effect of electric current on the microstructure and mechanical properties of hard-to-sinter materials with high melting point

Recycled kerf loss sludge SiC and Domestic production Si₃N₄ Sintering properties

3. Effect of electric current on the microstructure and mechanical properties of hard-to-sinter materials with high melting point

PART 1.

EFFECT OF ELECTRIC CURRENT ON THE MICROSTRUCTURE AND MECHANICAL PROPERTIES OF HARD-TO-SINTER MATERIALS WITH HIGH MELTING POINT

Background

The needs for structural ceramics

- ✓ Devices or parts for severe environment such as high T / strong mechanical load
- ✓ Materials with good properties especially mechanical properties
- ✓ Applications: bearing, automotive, aerospace, robot and etc.









aerospace.basf.com/

국내외 구조세라믹산업 현황 및 기술동향, (2010)

Materia		Advantages	Applications		
Ovida	SiO2	Low cost, Easy to process	Tube, Boat		
Oxide	AI2O3	High T/Wear/Corrosion resistance	Focus Ring		
	SiC	High T/Wear/Corrosion resistance Thermal shock resistance	Automotive engine parts, bearing		
Non oxide	AIN	High thermal conductivity	Heater Susceptor		
	Si3N4	Good wear-resistance at high T Thermal shock resistance	Wear-resistance material		

Background

5	2015	2014	2013	2012	2011	2010	2009	2008	2007	구분
4	39,301	34,804	30,829	27,315	24,207	21,457	18,969	16,771	14,830	ትደ
3	26,552	23,804	21,341	19,133	17,154	15,379	13,731	12,260	10,946	생산
2	10,035	8,864	7,830	6,917	6,110	5,398	4,768	4,212	3,721	수출
. 1	22,784	19,864	17,318	15,099	13,163	11,476	10,006	8,723	7,605	수입

Domestic market of structural ceramics







✓ Sustained growth, but raw materials/materials all imported

*출처: 신산업총연 특별기획보고서 (2006, 일본) Ceramic industry (2005)

- ✓ Technical competitiveness↓ (US, Japan)
 - -> Develop competitive process technique of structural ceramics

기관명	주요 내용
한국세라믹기술원	• 고열전도도, 고저항 질화알루미늄 소결기술 개발 * http://www.kicet.re.kr
KIST	 초고순도 탄화규소 원료개발 초고순도 반응소결 탄화규소 소결기술 개발 * http://www.kist.re.kr
재료연구소	 반응소결 질화규소 소결기술 개발 탄화규소의 저온 소결기술 개발 * http://www.kims.re.kr
KAIST	• 세라믹 소결의 치밀화 이론 분석 • 세라믹 소결의 비정상 입자성장 * http://www.kaist.ac.kr
SKC 솔믹스, 이노세라	• 대형 반응소결 탄화규소체 개발 * http://www.solmics.co.kr, www.inocera.co.kr
삼성전기	 나노 BaTiO₃를 이용한 극소형 고용량 MLCC 소결기술 개발 * http://www.samsungsem.co.kr

기관명	주요 내용
AIST	• 고열전도도 반응소결 질화규소 소결기술 개발 * http://unit.aist.go.jp/amri/
Yokohama National Univ.	• 질화규소계 세라믹스의 소결 및 역화특성 연구 • 질화규소 볼 베어링 소재의 내구성 연구 * http://www.ynu.ac.jp
Kyocera	• 비산화물계 대형 소결품 개발 * http://global.kyocera.com/prdct/fc/
Sumitomo	• 스프크 플라즈마 소결법의 개발 및 관련장비 개발 * http://www.shi.co.jp/sps/
Covalent Materials	 대형 반응소결 탄화규소체 개발 http://www.covalent.co.jp
NGK	• 질화알루미늄계 고열전도 세라믹 소재 개발 • 다공성 DPF 소재 개발 * http://www.ngk.co.jp
기관명	주요 내용
Oak-ridge National Lab.	• 질화규소 계면의 원자구조 및 기계적 물성 • 질화규소 터빈 블레이드의 실장시험 * http://www.oml.gov/
Ceradyne	• 비산화물계 방탄판의 개발 • 고온가압소결법의 연속공정개발 * http://www.ceradyne.com/
NASA	 ZrB₂계 초고은 세라믹스 개발 고온 세라믹 복합체 연구 http://www.nasa.gov/centers/glenn/

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Leading research institutes

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소재기술백서, (2011)

Material selection

- Silicon carbide (SiC)
 - Market conditions and application



SiC 소결체 및 분말에 관한 조사 (2013)

-> Widely used from high-strength to high-temperature semiconductor materials



- ➢ Silicon nitride (Si₃N₄)
 - ✓ Market conditions

Worldwide market of silicon nitride



In	le M	MT ; Metric ton			
	Japan	Germany	Others	Total	
2010	16 MT	5 MT	4 MT	25 MT	
2011	16 MT	10 MT	4 MT	30 MT	

수출입무역통계 (shippersgate.kita.net)

- Production volume of major companies
 - UBE (Japan) : 600 MT/year , Denka (Japan) : 100 MT/year
 - H.C Starck (Germany) : 100 MT/year
 - Others : Accumet Materials, Alzchem (US), EnoMaterial (China)

-> No domestic production company !!

- ➢ Silicon nitride (Si₃N₄)
 - ✓ Applications



Experimentals



Experimentals



Results



- Sintering $T \uparrow \rightarrow$ porosity $\downarrow \rightarrow$ Density \uparrow
- SPS ; low T densification by current/heat effects
 - short time -> grain growth↓
- page 11 Hardness(SPS) >> Hardness(CS)

Results



- Sintering T ↑ → porosity ↓ → Density ↑
- No current effect : microstructure evolution, mechanical properties

Discussion

- Silicon carbide
 - Properties depend on sintering conditions
 - -> temperature / time

-> paper published



Ceramics International



The effects of B_4C addition on the microstructure and mechanical properties of SiC prepared using powders recovered from kerf loss sludge

Jun-Young Cho a, Tae-ho An a, Sang-gu Ji a, Youngseok Kim b, Hyunick Shin b, Sarah Wonjung Kim c, Sung-Hwan Bae d, Miyoung Kim a, Chan Park a, e & 🖾

Silicon nitride

- Properties depend on sintering conditions
 - -> temperature / time
- ✓ HPed properties are relative higher than SPSed



PART 2.

RECYCLED KERF LOSS SLUDGE SIC AND DOMESTIC PRODUCTION SI3N4 SINTERING PROPERTIES



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Intro

Recycled kerf loss sludge SiC and Domestic production Si3N4 Sintering properties



Recycling technique



Cutting wire ; SiC abrasive

Composition	SiC (%)	Recycled SiC (%)		
SiC (%)	99	99.2		
Free-SiO2 (%)	0.75	0.51		
Free-Si (%)	0.05	0.21		
Free-C (%)	0.20	< 0.01		
Fe (ppm)	50	303		
Al (ppm)	250	28		
Ni (ppm)	<10	25		
V (ppm)	70	19		
Na (ppm)	<100	23		
Ca (ppm)	20	79		
Ti (ppm)	200	50		
Mg (ppm)	<100	10		
K (ppm)	20	15		





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Production technique of silicon nitride

	Carbothermal reduction	Method	Quality	Purity	Cost	Productivity	Company
	: 3SiO2 + 6C + 2N2 → Si3N4 +6CO (1300~	Carbothermal	Х	Х	0	0	
	Vapor phase reaction	Vapor phase reaction	0	0	\triangle	X	
	: 3SiCl4 + 16NH3 → Si3N4 + 12NH4Cl (130	0~1500 ^{rect} nitridation	\bigtriangleup	\triangle	0	0	DENKA H.C.Starck
	Direct niridation	Imide decomposition	0	0	X	0	UBE
	: 3Si + 2N2 → Si3N4 (1300~1500°C)	LT vapor- phase reaction	0	0	\triangle	0	
\succ	Imide decomposition	_					-

- Step 1: SiCl4 + 6NH3 \rightarrow Si(NH)2 + 4NH4Cl (-50~0°C, in solvent)
- Step 2: Solvent removal
- Step 3: $3Si(NH)2 \rightarrow amorphous-Si3N4 + 2NH3 (1000 \circ C)$
- Step 4: Si3N4 → crystal-Si3N4 (1300~1500 °C)





Low-temperature vapor-phase reaction

- Step 1: SiCl₄ + 6NH₃ \rightarrow Si(NH)₂ + 4NH₄Cl (25 °C) - Step 3 3Si(NH)₂ \rightarrow amorphous-Si₃N₄ + 2NH₃ (1000 °C)

- Step 4: $Si_3N_4 \rightarrow crystal-Si_3N_4$ (1300~1500 °C)

PART 3.

EFFECT OF ELECTRIC CURRENT ON SILICON NITRIDE CERAMIC ON SINTERING



Background

SPS(Spark plasma sintering) Apparatus and Features



- ♦ Apparatus
 - Mechanical press
 - Electrical energy supply
 - Electrodes
 - Container (mold/die)
 - Material (powder form)
- ♦ Features
 - Fast heating rate
 - Low sintering temperature
 - Short holding time

SPS Advantages and Application

- •Full densification with limited, or even inhibited grain growth
- Prevent undesirable phase transformations/reaction in the initial materials
- Every materials can sinter (metal/ceramic/composite)

Background \geq

Possible mold set-up on conductivity of ceramic materials



Conductive ceramic materials

- Conducting/insulating mold can be used
- Conducting mold -> general SPS
- Insulating mold -> SPS with high current density
- Insulating materials
 - Only conducting mold can be used

Effect of the current on ceramic sintering



J. Am. Ceram. Soc. 74 [6] 1217-25 (1991)

Background

✓ Comparison HP vs SPS

Effect of SPS on densification and mechanical properties of SiC

Materials: SiC + 5wt% AI_2O_3 + 2wt% Y_2O_3

Conditions: 1800°C, 30Mpa and 5min

Journal of the Ceramic Society of Japan 103 [7] 1995



-> The results suggest that the inside temperature of the sintered bodies during SPS was higher

than the measured temperature

Purpose

- To investigate the effect of current on sintering
- Experimental set-up
 - Thermal effect In-situ temperature measurement
 - Electrical effect Microstructure analysis



-> Comparison SPS and HP process (existence of electric current)

Experimental details

✓ In-situ temperature measurement



✓ Thermocouple



Results

The actual temperature in power during SPS



- Point 1 can measure temperature above 800°C
- Point 2 temperature is higher thank Point 1 in all range
- -> Pyrometer and thermocouple temperature calibration should be done at same position

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Electrical effect of SPS

- The actual temperature in power during SPS
 - * Temperature of SPS and HP should be same

In progress...



Addtional

- Si₃N₄ sintering using SPS
 - ✓ Temperature range: 1400-1600°C (with full density)
 - ✓ Actual temperature: 1600~1850°C (melting T: 1900°C) -> HP conditions

maximum



- Same temperature conditions will be secured
- > Other conditions also will be same (pressure, time and etc.)

Additional

Electrical property of Si₃N₄ ceramic / Etching



✓ Data: resistance of Si3N4 on temperature







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